

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A electronic circuit apparatus comprising:
a multilayered wiring board mounted with at least two electronic components;
a polyimide wiring board mounted with at least one heat generating component;
a heat sink having a higher heat conductivity than those of the multilayered wiring board and the polyimide wiring board, wherein the multilayered wiring board is fixed to one surface of the heat sink via adhesive and the polyimide wiring board is fixed to another surface of the heat sink via a adhesive;
an external connection terminal to which the multilayered wiring board and/or the polyimide wiring board is electrically connected; and
_____a thermosetting resin composition with which the entire surfaces of the multilayered wiring board and the polyimide wiring board, a part of the heat sink and a part of the external connection terminal are integrally molded.

2-6. (Canceled).

7. (Previously Presented) The electronic circuit apparatus according to claim 1, wherein a part of a passage for circulating a cooling medium is formed in an external layer of the electronic circuit apparatus.

8. (Previously Presented) A structure for mounting the automobile control unit

of claim 22, wherein the electronic circuit apparatus is fixed on the interior of an automatic transmission assembly of an automobile, and wherein said cooling medium is a transmission fluid.

9. (Previously Presented) A structure for mounting the automobile control unit of claim 22, wherein the electronic circuit apparatus is fixed on the interior of an engine compartment of an automobile, and wherein the cooling medium is an engine cooling water.

10. (Previously Presented) A structure for mounting the automobile control unit of claim 22, wherein the electronic circuit apparatus is fixed on the interior of an engine intake pipe of an automobile, and wherein the cooling medium is the air that passes in the engine intake pipe.

11. (Previously Presented) A structure for mounting the automobile control unit of claim 22, wherein at least two electronic circuit apparatuses are stacked on top of each other, and wherein the passage for circulating cooling medium is provided in the stacked electronic circuit apparatuses.

12. (Canceled).

13. (Previously Presented) The electronic circuit apparatus according to claim 1, wherein the heat sink is made of a metal compound with electrical conductivity, and wherein the adhesive is formed by an insulating organic paste.

14. (Previously Presented) The electronic circuit apparatus according to claim 1, wherein the heat sink is made of a clad material containing a copper alloy or copper.

15. (Previously Presented) The electronic circuit apparatus according to claim 1, wherein the adhesive is made of a thermosetting resin composition containing an epoxy resin and an inorganic filler.

16. (Previously Presented) The electronic circuit apparatus according to claim 1, wherein the multilayered wiring board comprises at least one ceramic substrate.

17. (Canceled).

18. (Previously Presented) The electronic circuit apparatus according to claim 1, wherein the polyimide wiring board is bent at least one end such that the polyimide wiring board is fixed to the another surface of the heat sink via the adhesive and fixed at the at least one end to the one surface of the heat sink.

19. (Previously Presented) The electronic circuit apparatus according to claim 18, wherein the multilayered wiring board and the polyimide wiring board are electrically connected.

20. (Previously Presented) The electronic circuit apparatus according to claim 7, wherein the part of the passage for circulating a cooling medium is formed in the thermosetting resin composition.

21. (Currently Amended) An automobile control unit comprising:
a multilayered wiring board mounted with at least two electronic components;
a polyimide wiring board mounted with at least one heat generating component;
a heat sink having a higher heat conductivity than those of the multilayered wiring board and the polyimide wiring board, wherein the multilayered wiring board is fixed to one surface of the heat sink via adhesive and the polyimide wiring board is fixed to another surface of the heat sink via a adhesive;
an external connection terminal to which the multilayered wiring board and/or the polyimide wiring board is electrically connected; and
_____a thermosetting resin composition with which the entire surfaces of the multilayered wiring board and the polyimide wiring board, a part of the heat sink and a part of the external connection terminal are integrally molded.

22. (Previously Presented) An automobile control unit according to claim 21, wherein a part of a passage for circulating a cooling medium is formed in an external layer of the electronic circuit apparatus.

23. (Previously Presented) An automobile control unit according to claim 21, wherein the heat sink is made of a metal compound with electrical conductivity, and wherein the adhesive is formed by an insulating organic paste.

24. (Previously Presented) An automobile control unit according to claim 21, wherein the heat sink is made of a clad material containing a copper alloy or copper.

25. (Previously Presented) An automobile control unit according to claim 21, wherein the adhesive is made of a thermosetting resin composition containing an epoxy resin and an inorganic filler.

26. (Previously Presented) An automobile control unit according to claim 21, wherein the multilayered wiring board comprises at least one ceramic substrate.

27. (Previously Presented) An automobile control unit according to claim 21, wherein the polyimide wiring board is bent at least one end such that the polyimide wiring board is fixed to the another surface of the heat sink via the adhesive and fixed at the at least one end to the one surface of the heat sink.

28. (Previously Presented) An automobile control unit according to claim 27, wherein the multilayered wiring board and the polyimide wiring board are electrically connected.

29. (Previously Presented) An automobile control unit according to claim 22, wherein the part of the passage for circulating a cooling medium is formed in the thermosetting resin composition.

30. (New) An automobile control unit according to claim 21, wherein the heat sink is made of a clad material having copper-invar-copper layers.

31. (New) The electronic circuit apparatus according to claim 1, wherein the

heat sink is made of a clad material having copper-invar-copper layers.